



Material Content Data Sheet



Sales Product Name	TLE9278BQX V33			Issued	31. January 2019			
MA#	MA004242868							
Package	PG-VQFN-48-31			Weight*	129.86 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.524	3.48	3.48	34839	34839
leadframe	inorganic material	phosphorus	7723-14-0	0.018	0.01		138	
	non noble metal	zinc	7440-66-6	0.072	0.06		552	
	non noble metal	iron	7439-89-6	1.433	1.10		11036	
wire	non noble metal	copper	7440-50-8	58.193	44.82	45.99	448115	459841
	non noble metal	copper	7440-50-8	0.572	0.44	0.44	4404	4404
	encapsulation	organic material	carbon black	1333-86-4	0.182	0.14		1402
	plastics	epoxy resin	-	7.706	5.93		59338	
	inorganic material	silicondioxide	60676-86-0	52.787	40.65	46.72	406485	467225
leadfinish	non noble metal	tin	7440-31-5	2.596	2.00	2.00	19993	19993
plating	noble metal	silver	7440-22-4	0.614	0.47	0.47	4727	4727
glue	plastics	epoxy resin	-	0.268	0.21		2063	
	noble metal	silver	7440-22-4	0.897	0.69	0.90	6908	8971
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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